



# First Electrically Pumped Hybrid Silicon Laser

*Sept 18<sup>th</sup> 2006*

*The information in this  
presentation is under embargo  
until 9/18/06– 10:00 AM PST*



# Agenda

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**Dr. John Bowers**

*Professor, UC Santa Barbara*

- What We are Announcing
- Silicon Photonics Overview
- Lasers & Light Emission with Silicon Photonics
- Joint Collaboration – Hybrid Silicon Laser
- Hybrid Silicon Laser Test Results
- Summary

# What We are Announcing

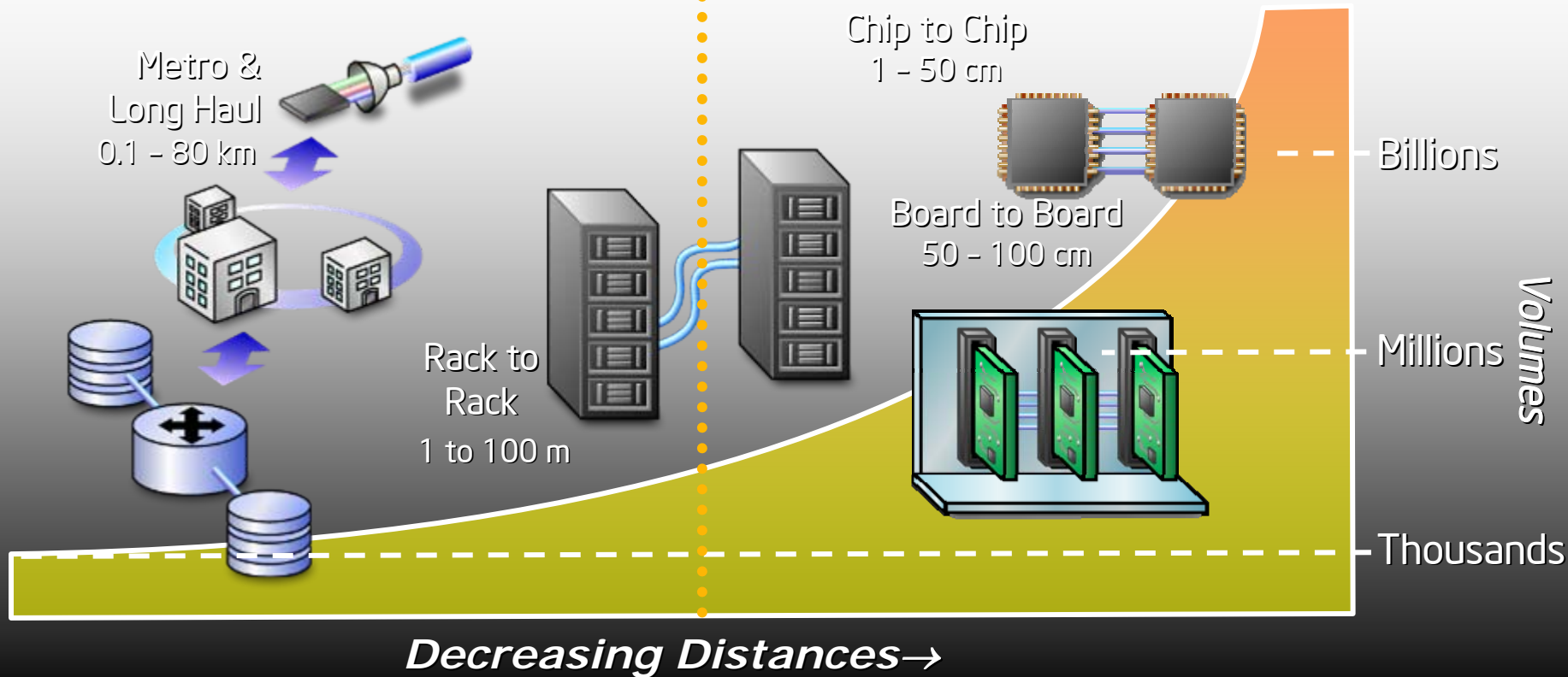
- Research Breakthrough: 1st Electrically pumped Hybrid Silicon Laser
  - A joint collaboration between UCSB and Intel Corporation
  - Combines the light emitting capabilities of Indium phosphide with the high volume, low cost capabilities of silicon
  - Addresses one of the last major hurdle to silicon photonic chips
- Vision:
  - Build chips containing 10 to 100s of Hybrid Silicon Lasers
  - Built using high-volume, low cost manufacturing processes
  - Enables terabit optical links
- Background
  - Silicon is a poor light emitter while Indium phosphide based materials are great light emitters
  - However, Indium phosphide lasers are expensive to manufacture
  - Novel design combined with a manufacturing process where a unique “glass glue” was used to bond the two materials together

# The Photonic Dilemma

- Fiber can carry much more bandwidth than copper
- However, it is much more expensive.....

# Today's High Speed Interconnects

Optical : Copper



**Goal: Drive optical to high volumes and low costs**

*Photonics: The technology of emission, transmission, control and detection of light (photons) aka fiber-optics & opto-electronics*

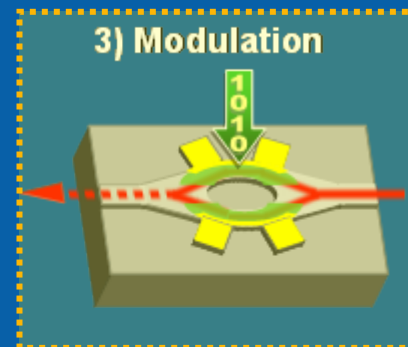
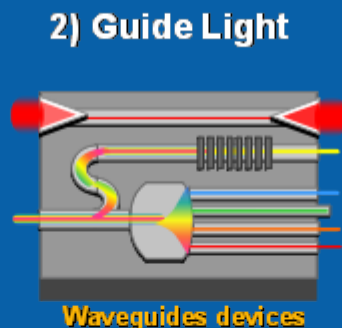
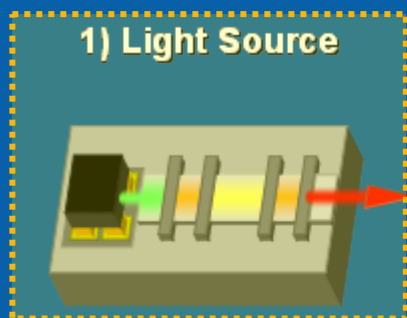
*Today: Most photonic devices made with exotic materials, expensive processing, complex packaging*

*Silicon Photonics Vision: Research effort to develop photonic devices using silicon as base material and do this using standard, high volume silicon manufacturing techniques in existing fabs*

**Benefit: Bring volume economics to optical communications**

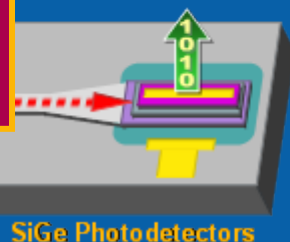


# Intel's Silicon Photonics Research

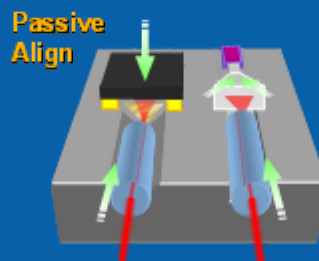


**Continuous Wave  
Silicon Raman  
Laser**  
(Feb '05)

4) Photo-detection



5) Low Cost Assembly



6) Intelligence



**1GHz (Feb '04)  
10 Gb/s (Apr '05)**

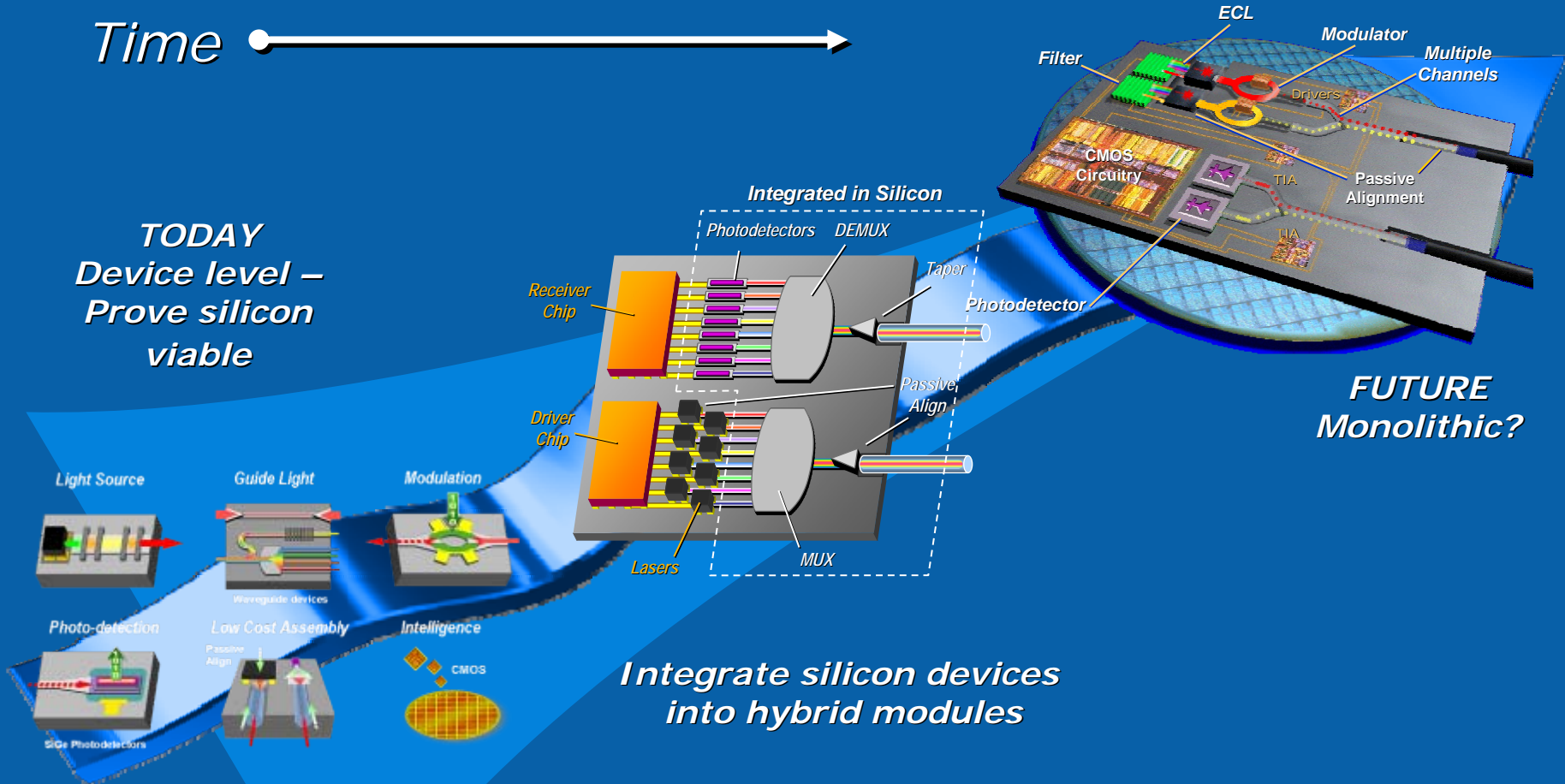
**Electrically  
Pumped  
Hybrid  
Silicon laser**  
(September 2006)

**First: Innovate to prove silicon is a  
viable optical material**

# Integration Vision

Time →

**TODAY**  
Device level –  
Prove silicon  
viable

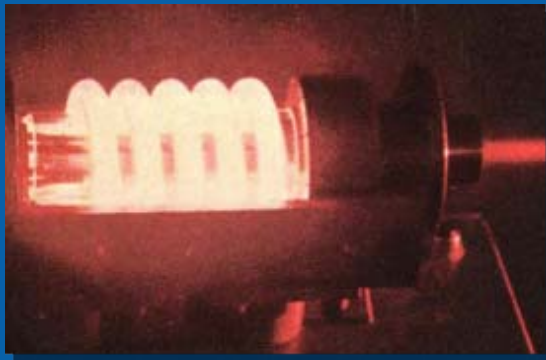
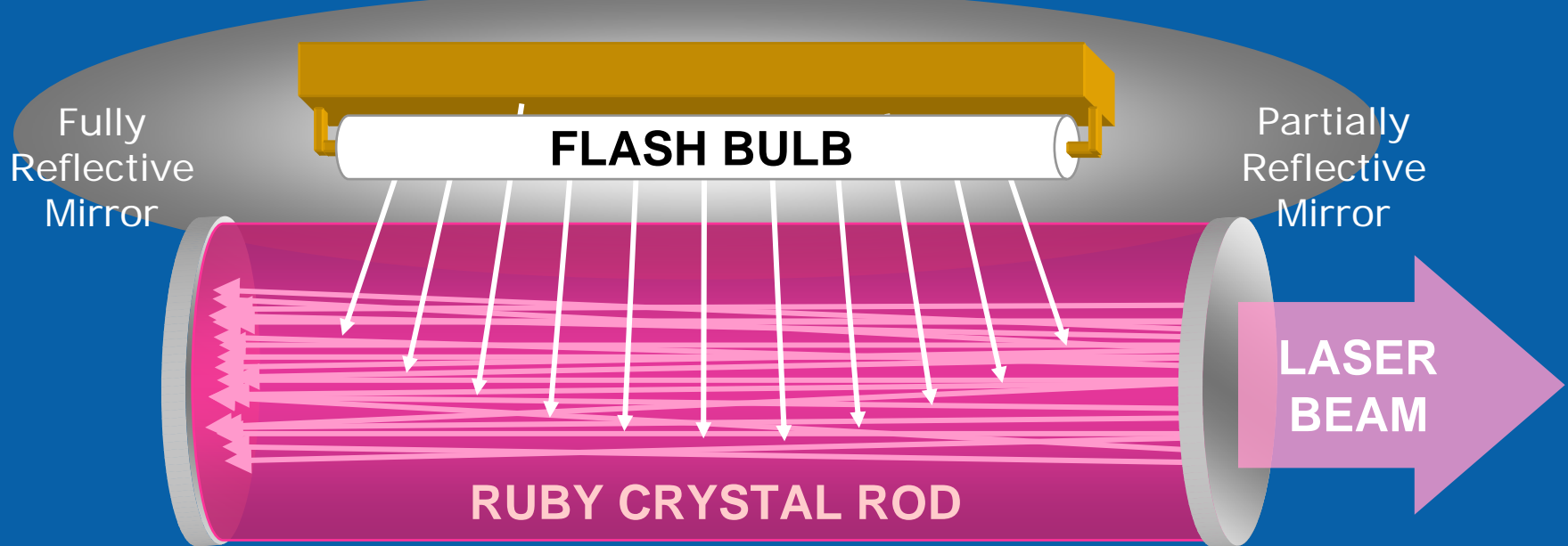


Increasing silicon  
integration over time



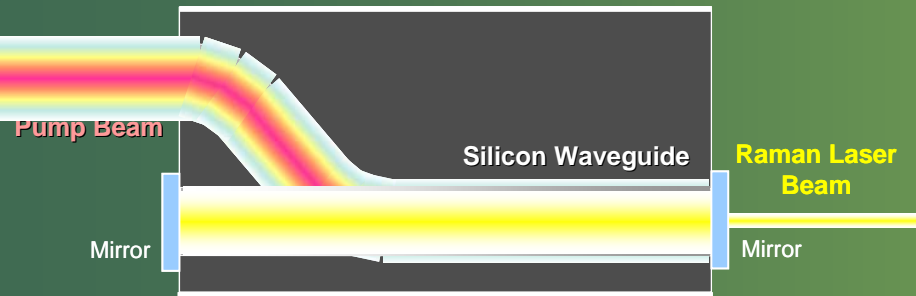
# The First Laser

Developed by Maiman, this ruby laser used a flash bulb as an optical pump



# Raman Laser

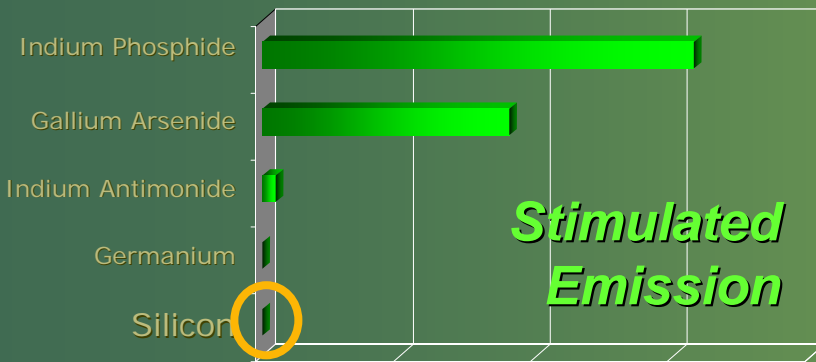
*Announced in Feb 2005*



## First CW silicon laser

- Research Breakthrough
- Based on the Raman effect
- Optically pumped

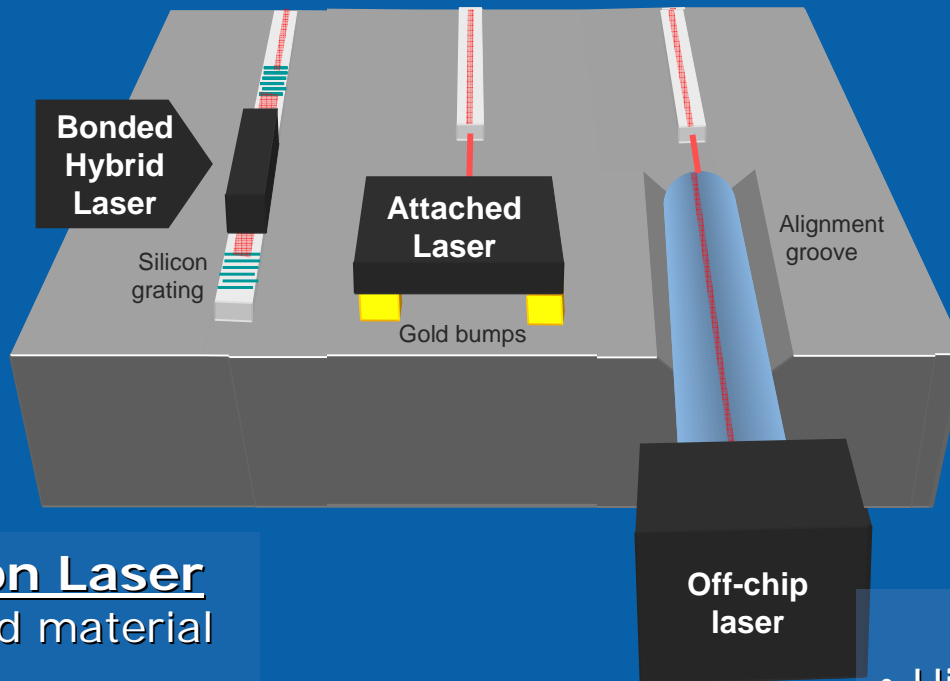
*Radiative recombination coefficient ( $10^{-12}\text{cm}^3/\text{s}$ )*



## Want: Electrically Pumped

- Silicon is an indirect bandgap material
- Poor radiative recombination coefficient
- Result: Silicon emits heat, few photons

# Options for Integrating Light Sources



## Hybrid Silicon Laser

- Bond InP based material to Silicon
- No alignment
- Many lasers with one bonding step
- Amenable to high integration
- Potentially lowest cost

## Direct Attached Laser

- Tight alignment tolerances
- Requires gold metal bonding
- Passive alignment challenges
- Less Expensive

## Off-chip Laser

- High power laser required
- Requires fiber attach
- Non-integrated solution
- Expensive

# Joint Intel / UCSB Collaboration

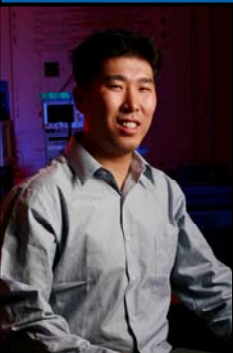
- Goal: Create a hybrid silicon laser
- Combine the light emitting properties of Indium phosphide with light routing and manufacturability properties of silicon

## Joint team and 3 year research grant



UCSB – Indium phosphide and wafer bonding expertise

- Alex Fang (ex Intel intern)
- Professor John Bowers
- Hyundai Park



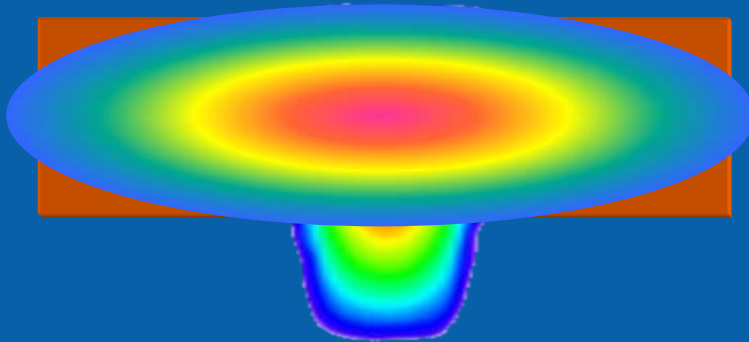
Intel – Silicon and manufacturing expertise

- Dr Richard Jones
- Oded Cohen
- Dr Mario Paniccia



# Hybrid Silicon Laser

## *Using Evanescent Coupling*

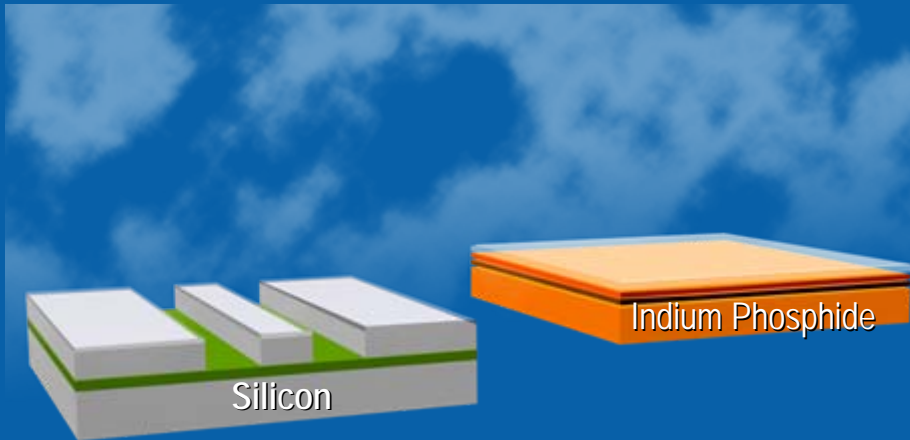


- We start with a cross sectional view of an Indium Phosphide waveguide
- When a voltage is applied to the InP it will begin to emit light
- If we bring a silicon waveguide up to the InP, light will couple into the Si waveguide
- This is evanescent coupling



**Challenge: How do you bond these two materials together?**

# Bonding Process

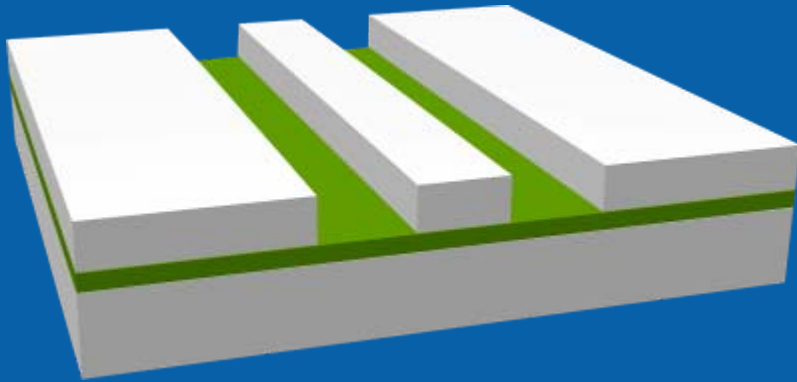


The Hybrid Silicon Laser used a unique bonding technique

- **Previous attempts used crystal growth**
  - Difficult to overcome lattice mismatch/threading dislocation
  - Causes poor performance
- **Benefits of the UCSB/Intel approach**
  - Removes issue with lattice mismatch
  - Plasma process produces ~25 atom thick “glass-glue”
  - This “glass-glue” efficiently bonds the two materials
  - Low temperature manufacturable process



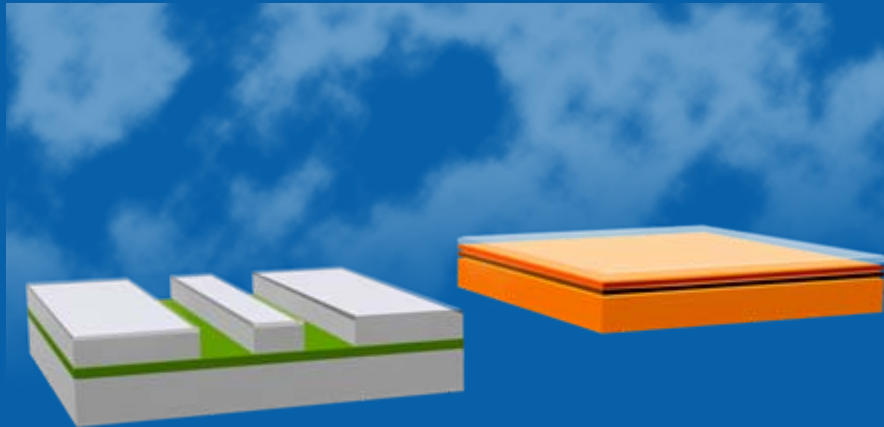
# Process Animation



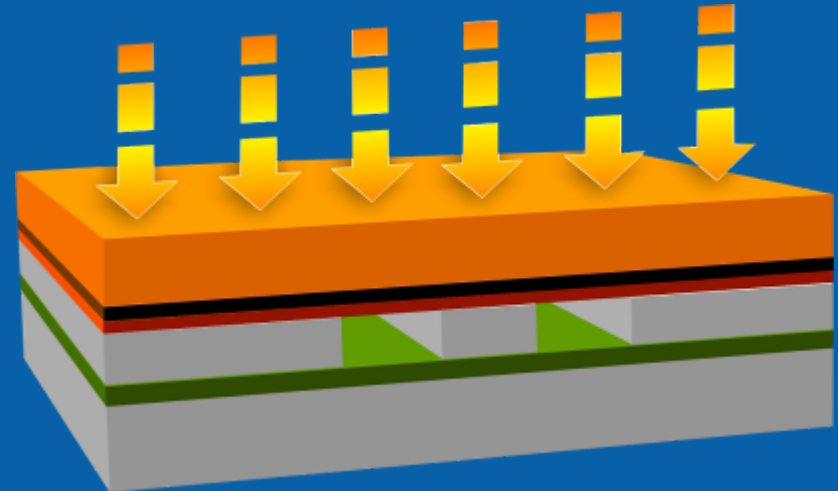
1) A waveguide is etched in silicon



2) The Indium phosphide is processed to make it a good light emitter

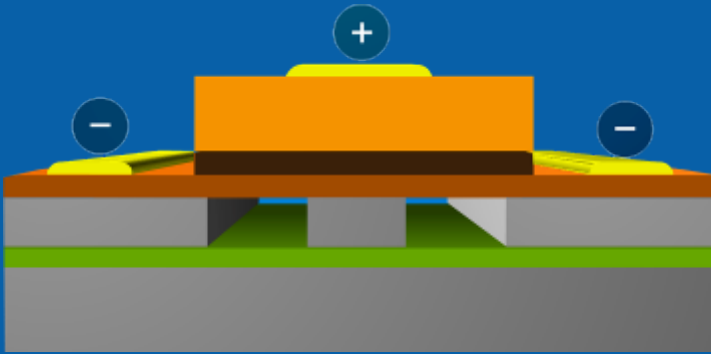


3) Both materials are exposed to the oxygen plasma to form the "glass-glue"

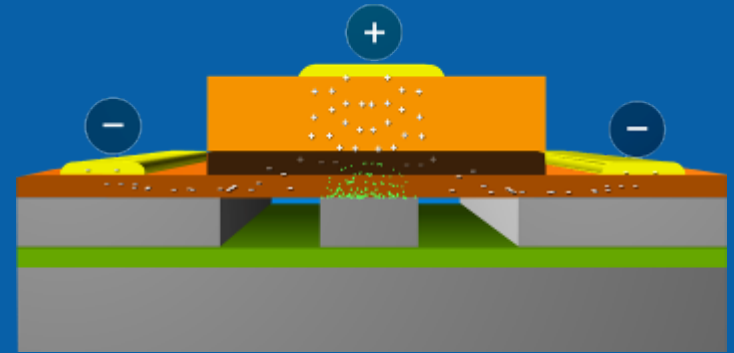


4) The two materials are bonded together under low heat

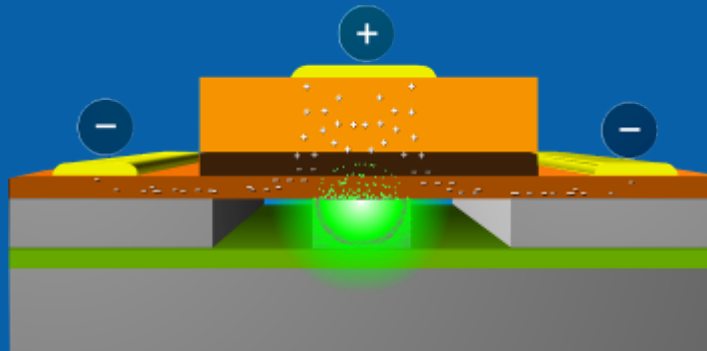
# Process Animation



5) The Indium phosphide is etched and electrical contacts are added



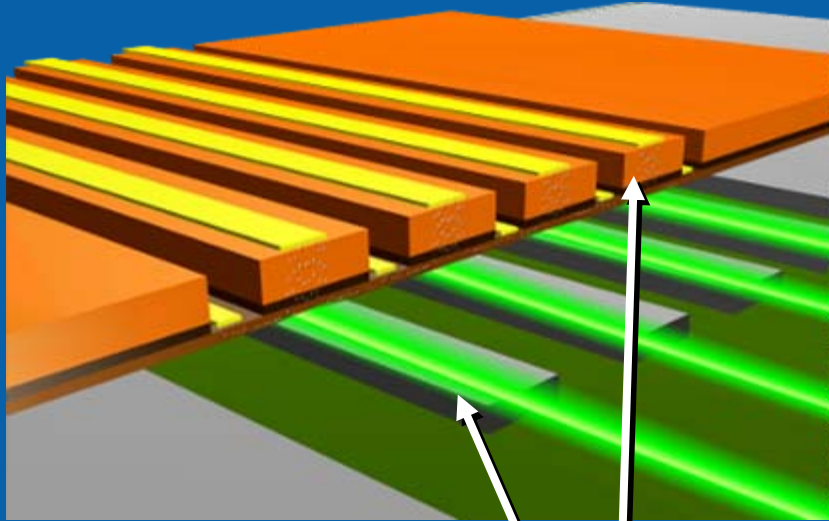
6) Photons are emitted from the Indium Phosphide when a voltage is applied



7) The light is coupled into the silicon waveguide which forms the laser cavity. Laser light emanates from the device.

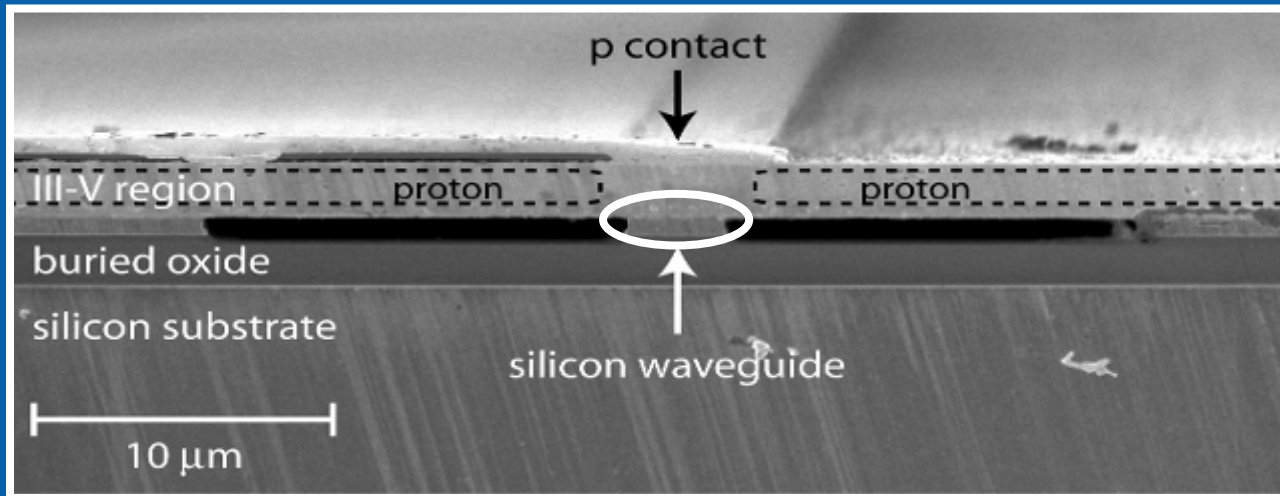
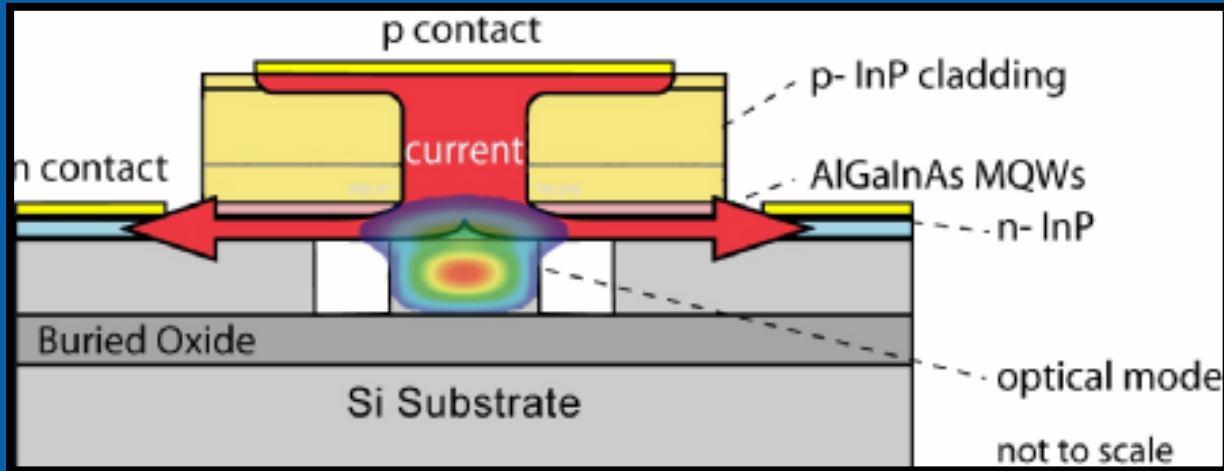
# Hybrid Silicon Laser

*How we create a laser in silicon*



- The Indium Phosphide emits the light into the silicon waveguide
- The silicon acts as laser cavity:
  - Silicon waveguide routes the light
  - End Facets are reflectors/mirrors
  - Light bounces back and forth and get amplified by InP based material

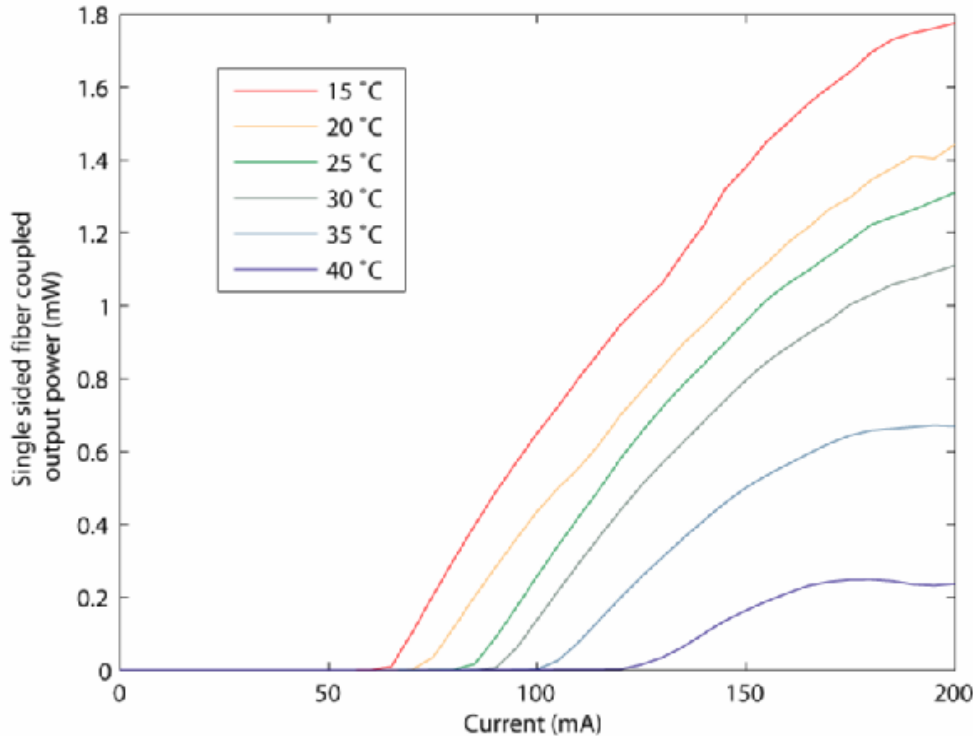
# Hybrid Laser Structure



*SEM (Scanning Electron Microscope) Photograph*

# First Electrically Pumped CW Lasing

Measured Laser output power vs current



Threshold Voltage = 2V

## Threshold Current

- At 65 mA with plans to get to ~ 20 mA

## Output power

- At 1.8 mW, Good for optical interconnects

## Temperature

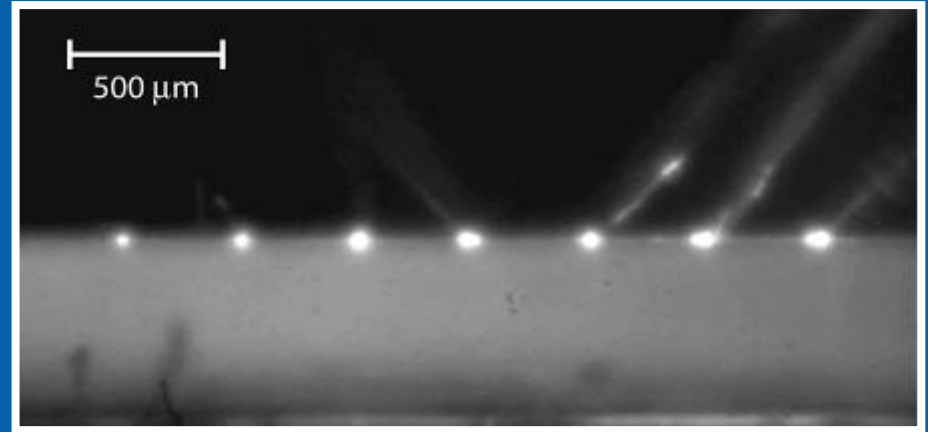
- Operating at 40 C with plans for > 70 C

Initial testing shows good performance

# Electrically Pumped Laser Wavelength

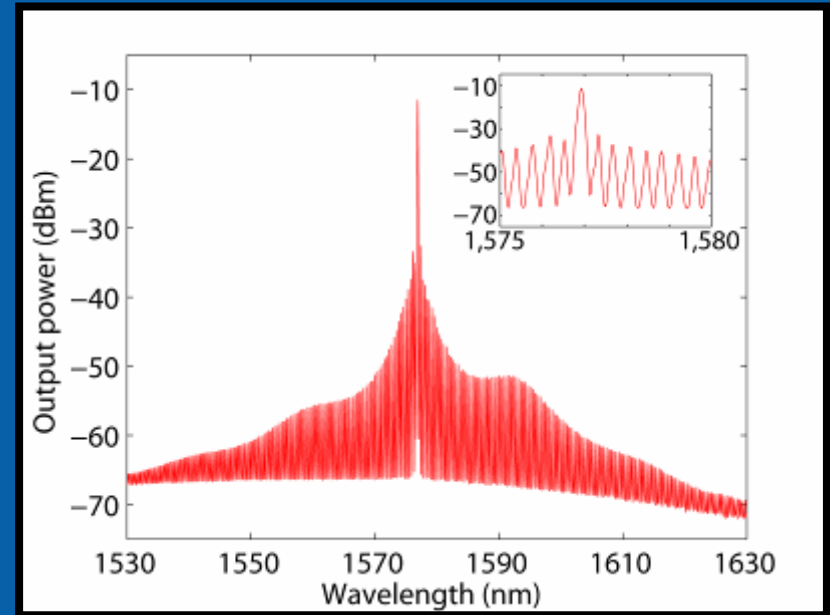
- 7 Hybrid Silicon Lasers

- All fabricated with a single bond step
- Up to 36 lasers are on one die



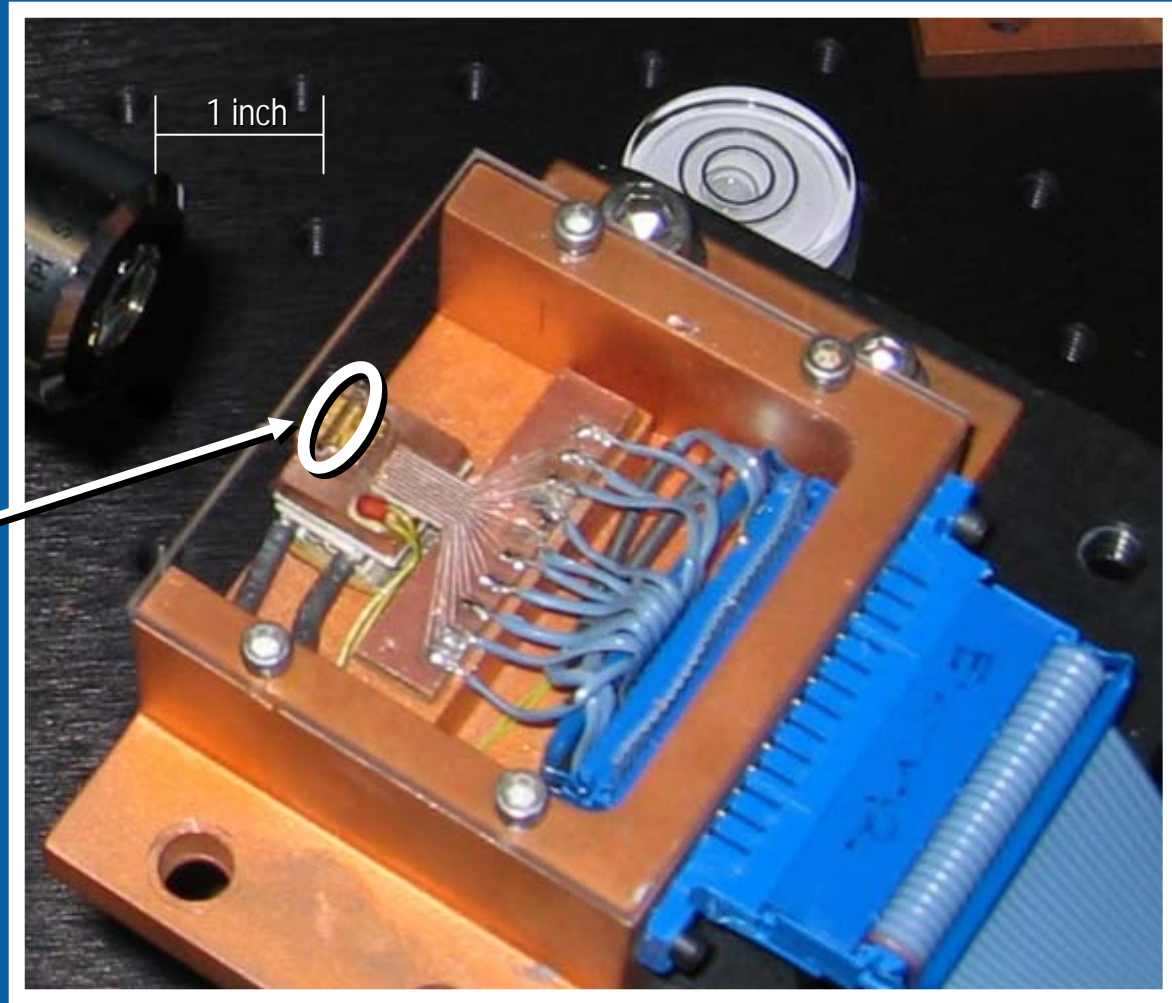
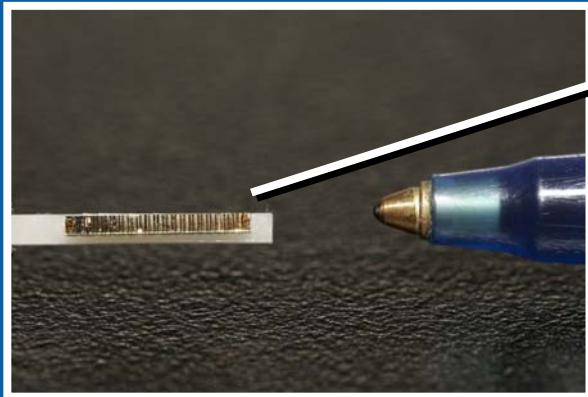
- **Lasing Output at 1577nm**

- This is adjustable via modifying the silicon waveguides

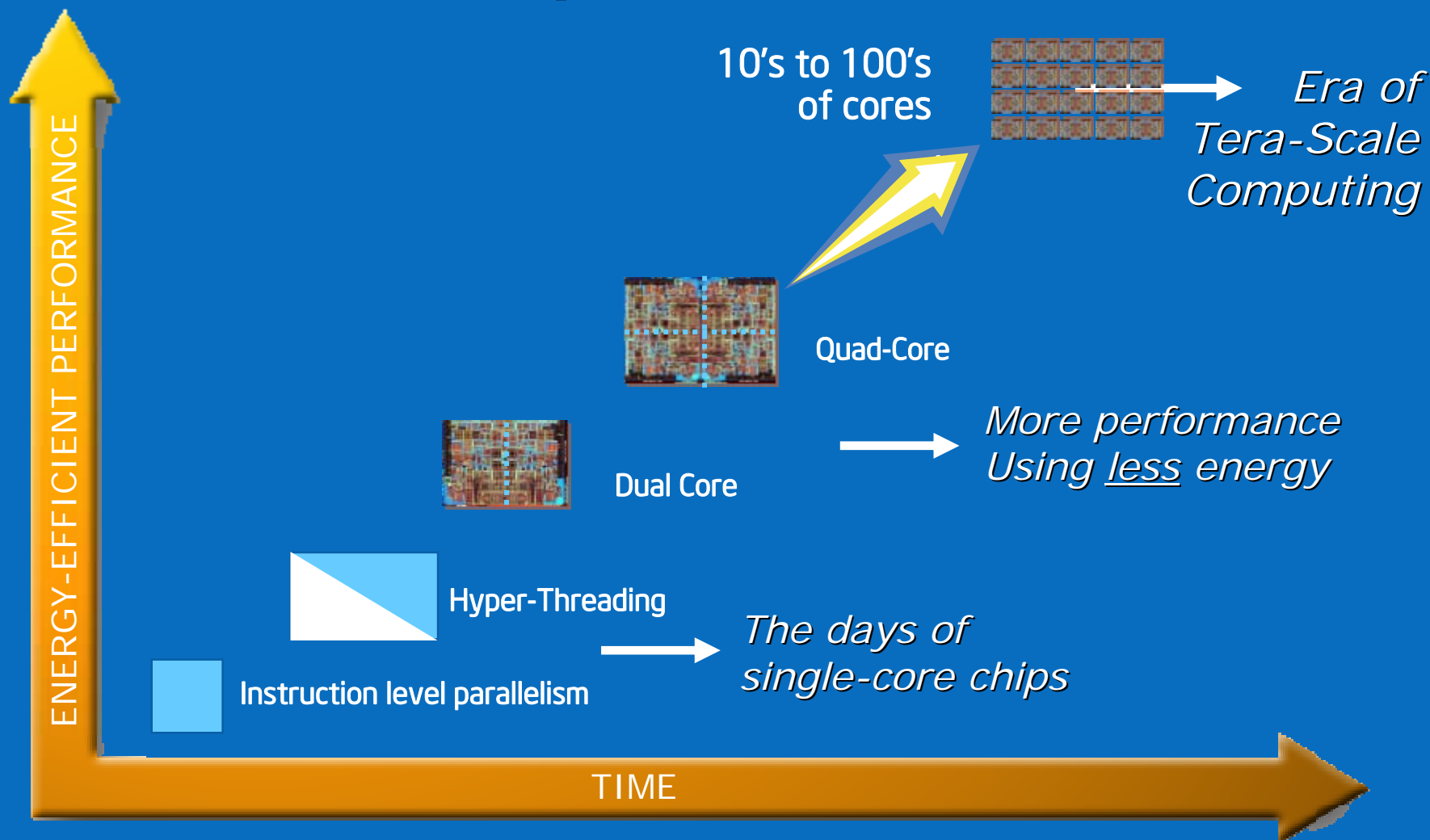




# Silicon Hybrid Laser



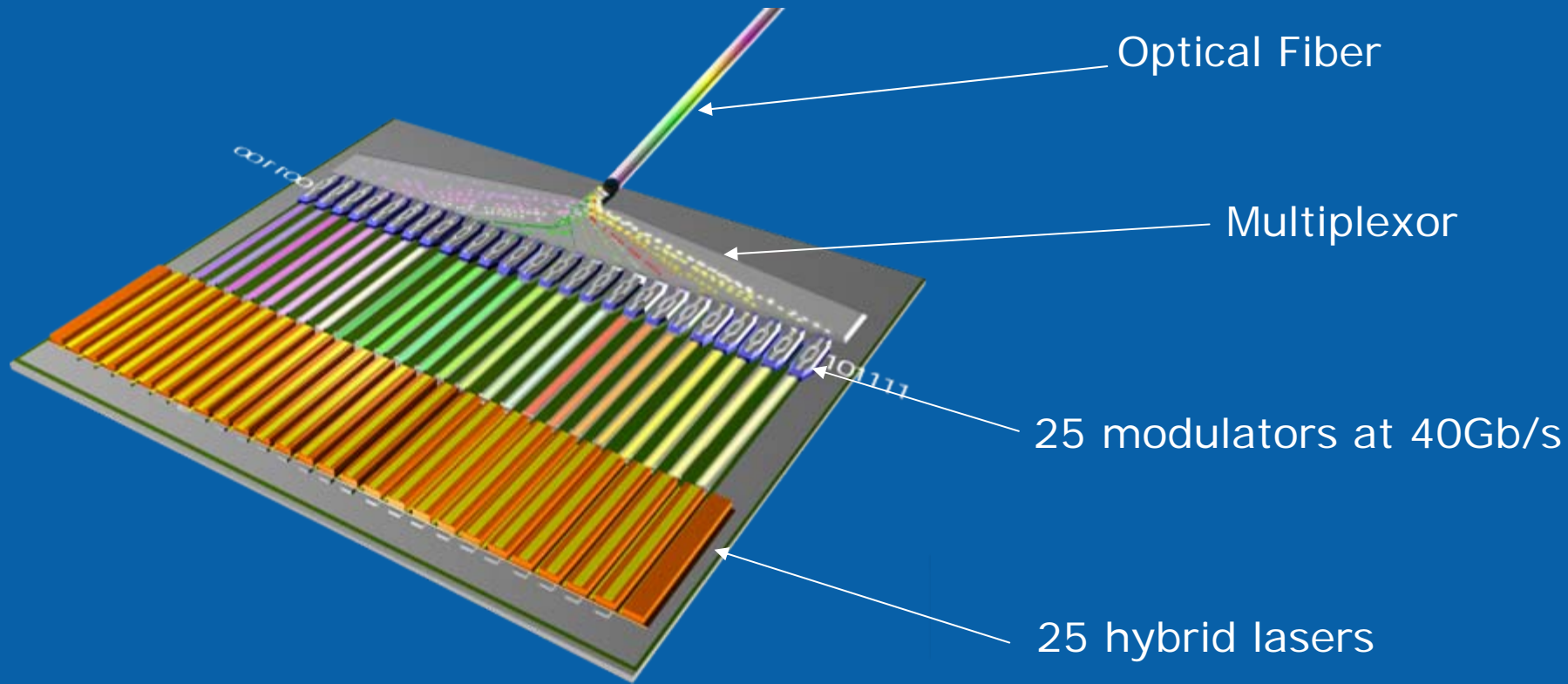
# Tera-leap to Parallelism:



**All this compute capability may require  
high speed optical links**

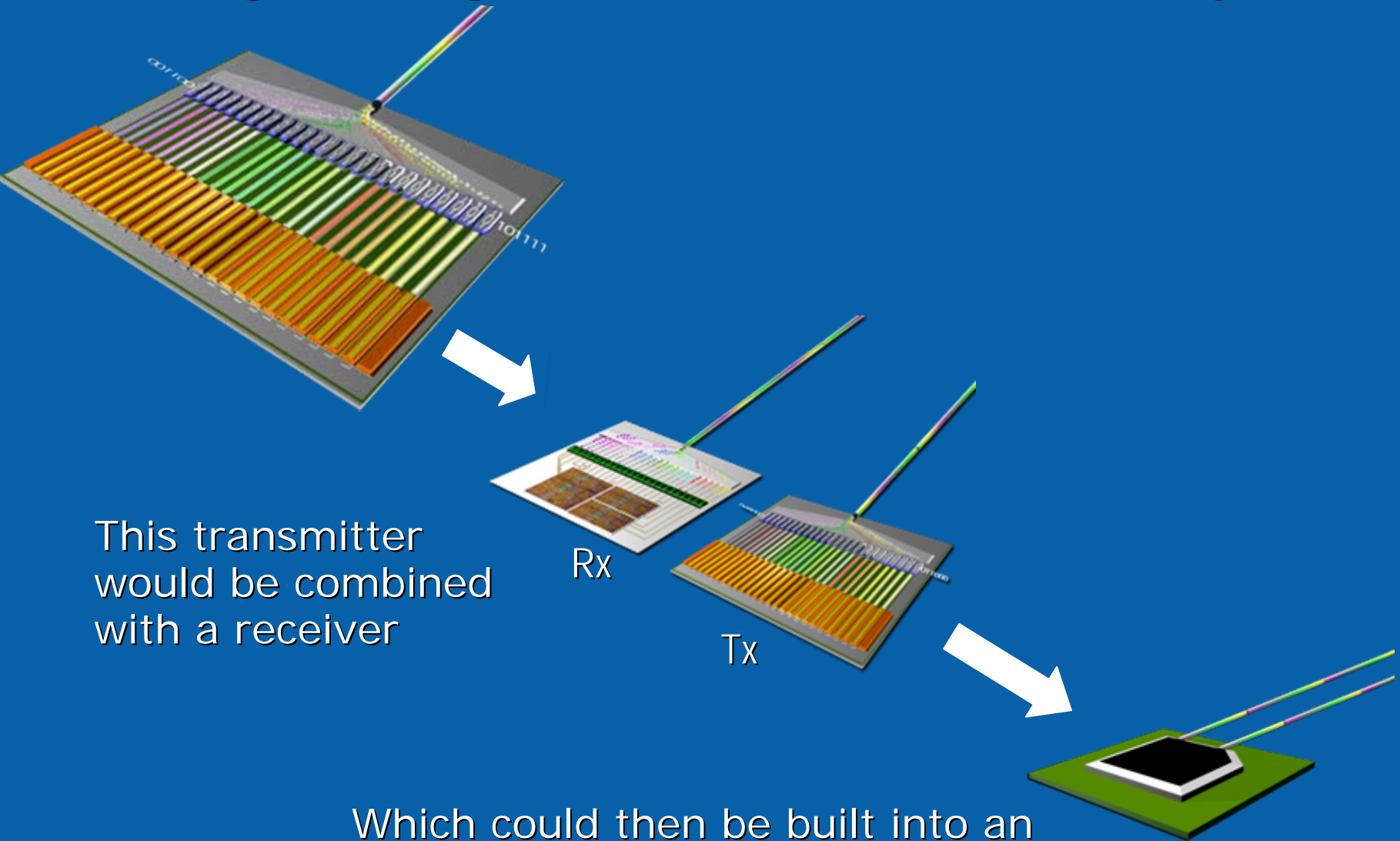


# High Integration



**An future integrated terabit per second  
optical link on single chip**

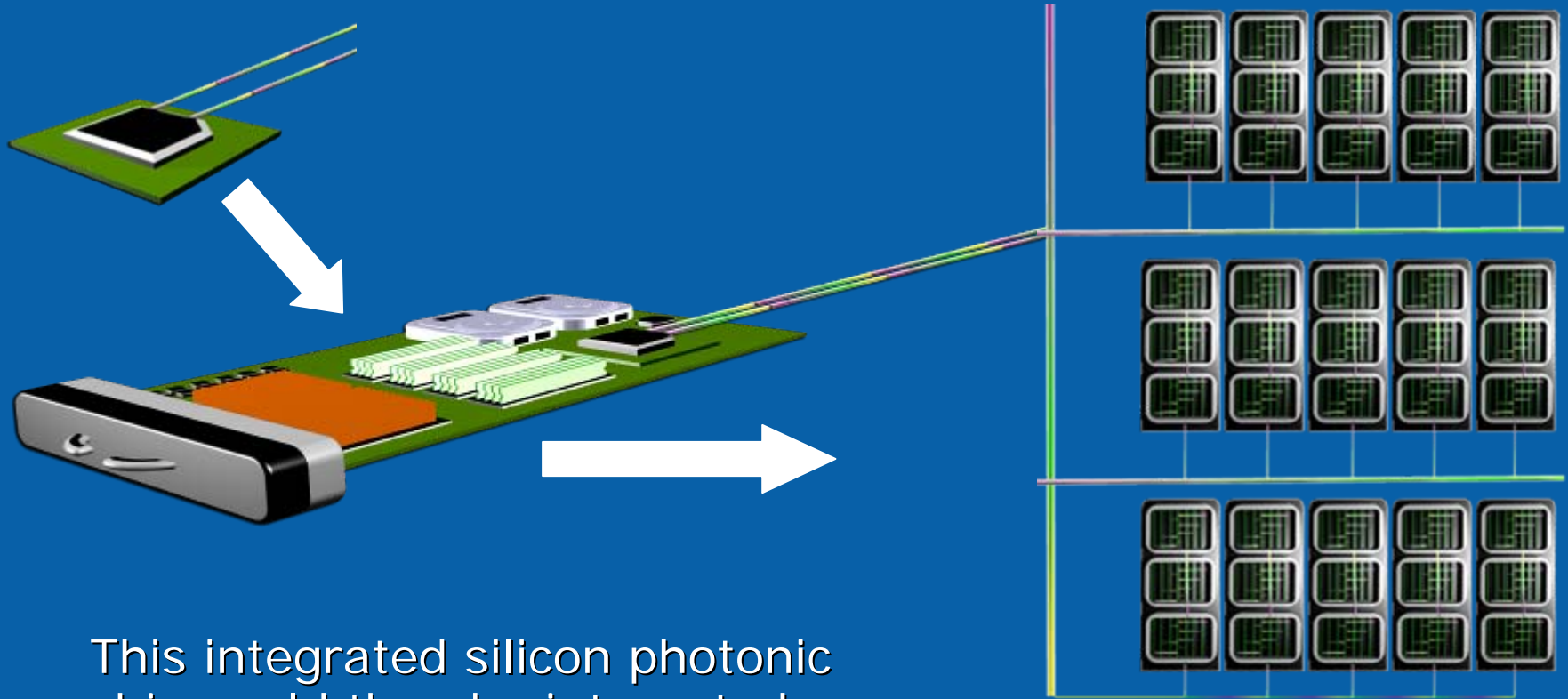
# Integrating into a Tera-scale System



This transmitter would be combined with a receiver

Which could then be built into an integrated, silicon photonic chip!!

# Integrating into a Tera-scale System



This integrated silicon photonic chip could then be integrated into computer boards

And this board could be integrated into a Tera-scale system



# Summary

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Acknowledgements: UCSB and Professor Bowers would like to thank Jag Shah and DARPA for funding some of this research.